

APTB1615ESGC-F01

1.6 x 1.5 mm Bi-Color SMD Chip LED Lamp



DESCRIPTIONS

- The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode
- The Super Bright Green source color devices are made with Gallium Phosphide Green Light Emitting Diode

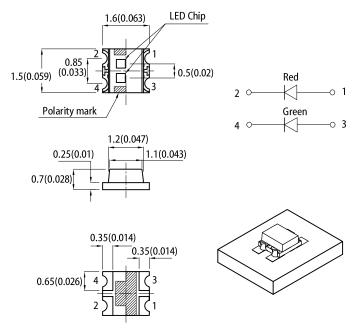
FEATURES

- 1.6 mm x 1.5 mm SMD LED, 0.7 mm thickness
- · Low power consumption
- · Wide viewing angle
- · Ideal for backlight and indicator
- Package: 2000 pcs / reel
- Moisture sensitivity level: 3
- · Tinned pads for improved solderability
- · RoHS compliant

APPLICATIONS

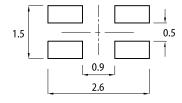
- Backlight
- · Status indicator
- · Home and smart appliances
- · Wearable and portable devices
- · Healthcare applications

PACKAGE DIMENSIONS



RECOMMENDED SOLDERING PATTERN

(units: mm; tolerance: \pm 0.1)



- 1. All dimensions are in millimeters (inches).
- Tolerance is ±0.2(0.008") unless otherwise noted.
 The specifications, characteristics and technical data described in the datasheet are subject to
- change without prior notice.

 4. The device has a single mounting surface. The device must be mounted according to the specifications.

SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 20mA [2]		Viewing Angle [1]	
			Min.	Тур.	201/2	
	■ High Efficiency Red		8			
APTB1615ESGC-F01	(GaAsP/GaP)	- Water Clear	*3	*7	4500	
	Super Bright Green (GaP) Super Bright Green 5 12 *5 *12		5	12	150°	
		*12				

Notes.

1. 61/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity / luminous flux: +/-15%.

* Luminous intensity value is traceable to CIE127-2007 standards.





ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Symbol	Emitting Color	Va	lue	Unit
	5,	g	Тур.	Max.	
Wavelength at Peak Emission I _F = 20mA	λ_{peak}	High Efficiency Red Super Bright Green	627 565	-	nm
Dominant Wavelength I _F = 20mA	λ _{dom} ^[1]	High Efficiency Red Super Bright Green	617 568	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 20mA	Δλ	High Efficiency Red Super Bright Green	45 30	-	nm
Capacitance	С	High Efficiency Red Super Bright Green	15 15	-	pF
Forward Voltage I _F = 20mA	V _F ^[2]	High Efficiency Red Super Bright Green	2.0 2.2	2.5 2.5	V
Reverse Current (V _R = 5V)	I _R	High Efficiency Red Super Bright Green	-	10 10	uA

Notes:

ABSOLUTE MAXIMUM RATINGS at $T_A=25$ °C

Parameter	Symbol	Value		
	- Cymbol	High Efficiency Red	Super Bright Green	Unit
Power Dissipation	P_{D}	75	62.5	mW
Reverse Voltage	V _R	5	5	V
Junction Temperature	TJ	125	110	°C
Operating Temperature	T _{op}	-40 To +85		°C
Storage Temperature	T _{stg}	-40 To +85		°C
DC Forward Current	I _F	30	25	mA
Peak Forward Current	I _{FM} ^[1]	160	140	mA
Electrostatic Discharge Threshold (HBM)	-	8000	8000	V

Notes:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

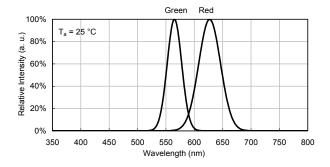


^{1.} The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd:±1nm.)
2. Forward voltage: ±0.1V.
3. Wavelength value is traceable to CIE127-2007 standards.
4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

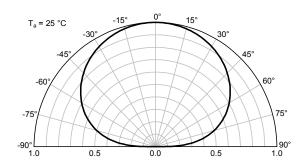


TECHNICAL DATA

RELATIVE INTENSITY vs. WAVELENGTH

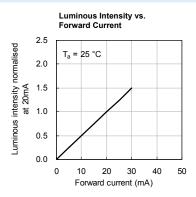


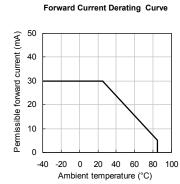
SPATIAL DISTRIBUTION

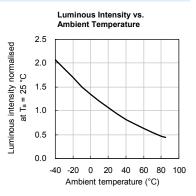


HIGH EFFICIENCY RED

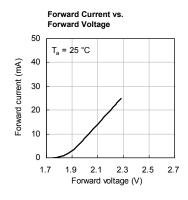
Forward Current vs. **Forward Voltage** 50 T_a = 25 °C Forward current (mA) 40 30 20 10 0 1.9 2.1 1.5 Forward voltage (V)

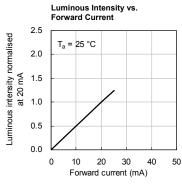


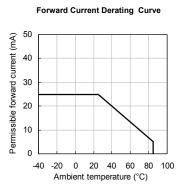


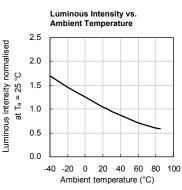


SUPER BRIGHT GREEN









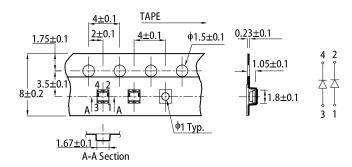


REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS

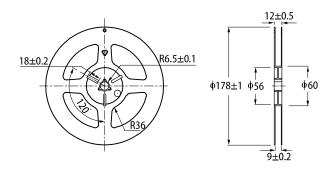
300 above 255°C (°C) 260°C max. 30s max 10s max. 250 3°C/s max. 6°C/s max. 200 150 Temperature pre-heating 100 150~200°C above 217°C 60~120s 60~150s 50 . 25℃ 0 100 150 200 50 250 0 300 (sec) Time

- 1. Don't cause stress to the LEDs while it is exposed to high temperature.
 2. The maximum number of reflow soldering passes is 2 times.
 3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

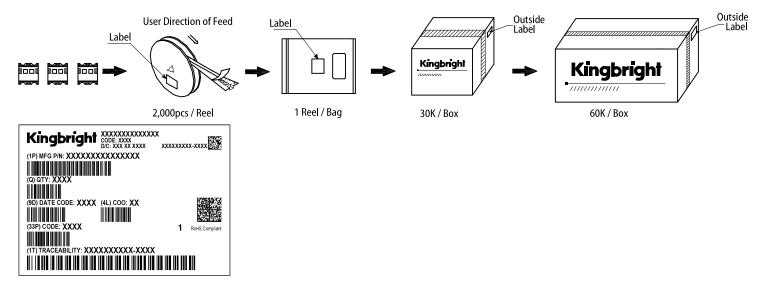
TAPE SPECIFICATIONS (units:mm)



REEL DIMENSION (units: mm)



PACKING & LABEL SPECIFICATIONS



PRECAUTIONARY NOTES

- The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.

 The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening
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